

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1. (Canceled).

Claim 2. (Original): A method for manufacturing a ceramic circuit board, comprising the steps of:

preparing a ceramic substrate having a through hole, a metal column with brazing material, and at least two pieces of metal circuit plates, said metal column with brazing material being made 40 to 140 μm longer relative to a thickness of the ceramic substrate, by coating both ends of a metal column which is 0 to 150 μm shorter relative to the thickness of the ceramic substrate, with a brazing material;

arranging the metal column with brazing material within the through hole of the ceramic substrate, and arranging the metal circuit plates on both surfaces of the ceramic substrate in such a way as to stop up the through hole; and

bonding, after melting the brazing material by heating, the metal column and the metal circuit plates together via the molten brazing material.

Claims 3 and 4 (Canceled).

Claim 5. (Original): The method for manufacturing the ceramic circuit board of claim 2,

wherein the metal circuit plate is made of copper or aluminum.

Claim 6. (Original): The method for manufacturing the ceramic circuit board of claim 2,

wherein the metal column is made of copper or aluminum.

Claim 7. (Canceled).

Claim 8. (Original): The method for manufacturing the ceramic circuit board of claim 2,

wherein a space secured between an inner wall surface of the through hole and an outer wall surface of the metal column is kept in a range of 30 to 200 μm in length.

Claims 9-15 (Canceled).